

Component PAPI: Measuring Multiple Counter Domains

Presented by

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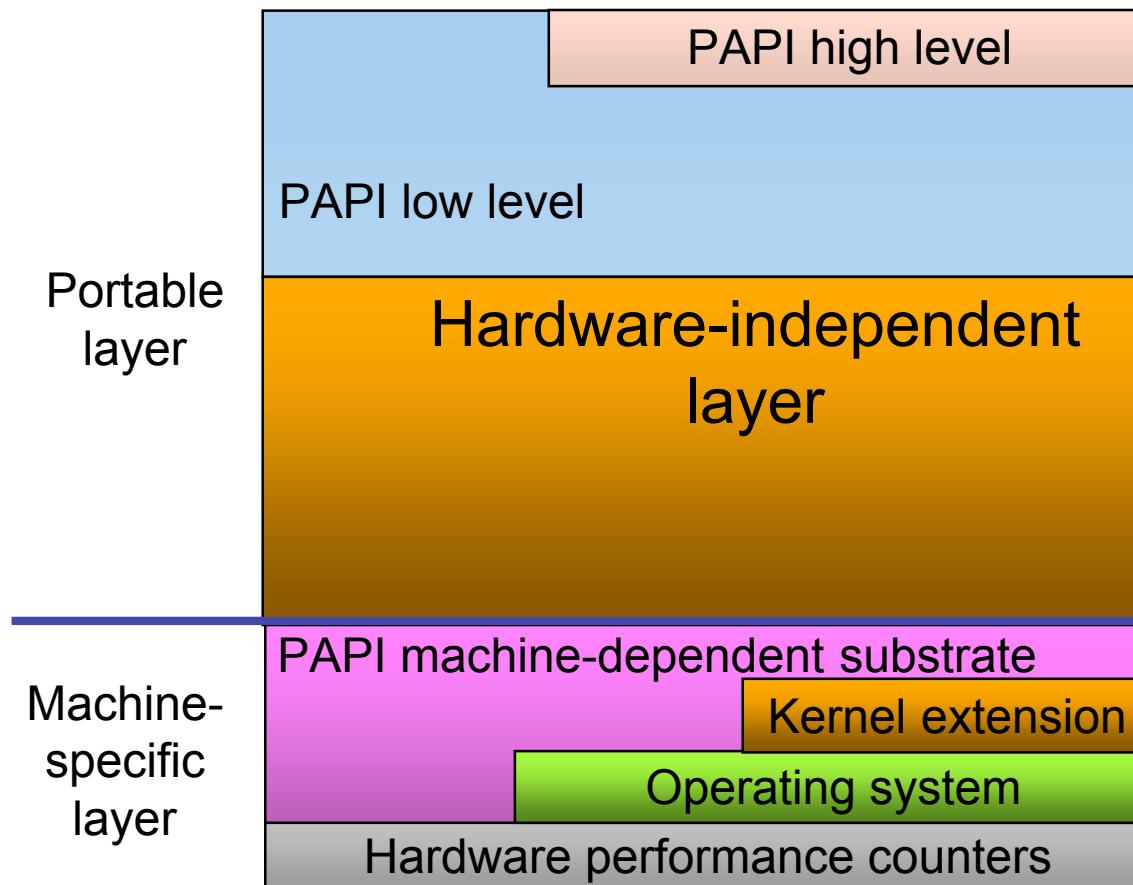
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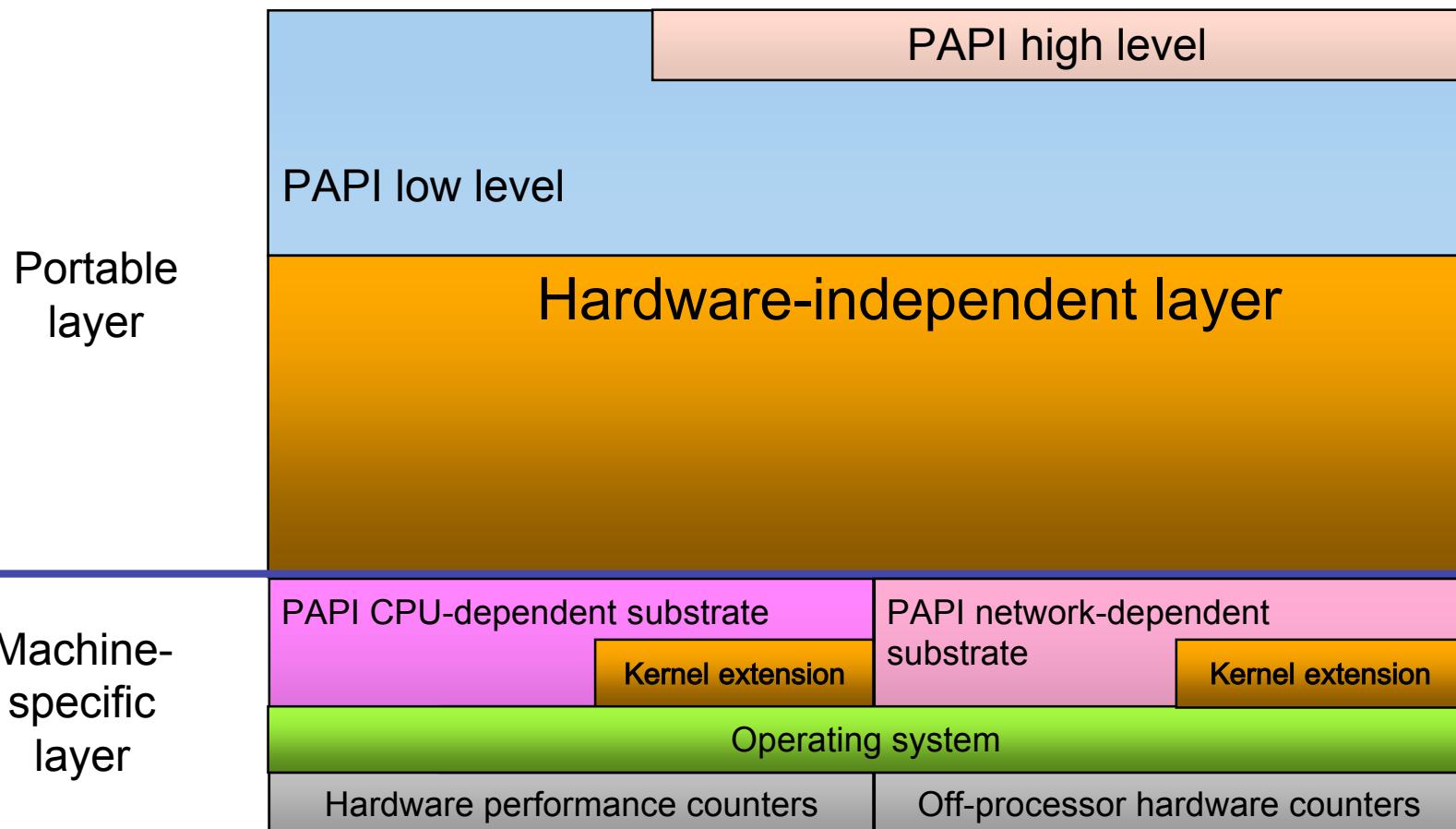
Motivation

- Increasing CPU speeds and densities places greater importance on
 - Thermal health and management and
 - Power consumption.
- Higher processor counts make communications metrics more critical:
 - Bandwidth,
 - Latency,
 - Dropped packets, and
 - Bytes transferred.
- Industry standard interfaces don't exist to measure these metrics.
- Hybrid machines require simultaneous access to multiple processor counter substrates.

Monolithic PAPI design

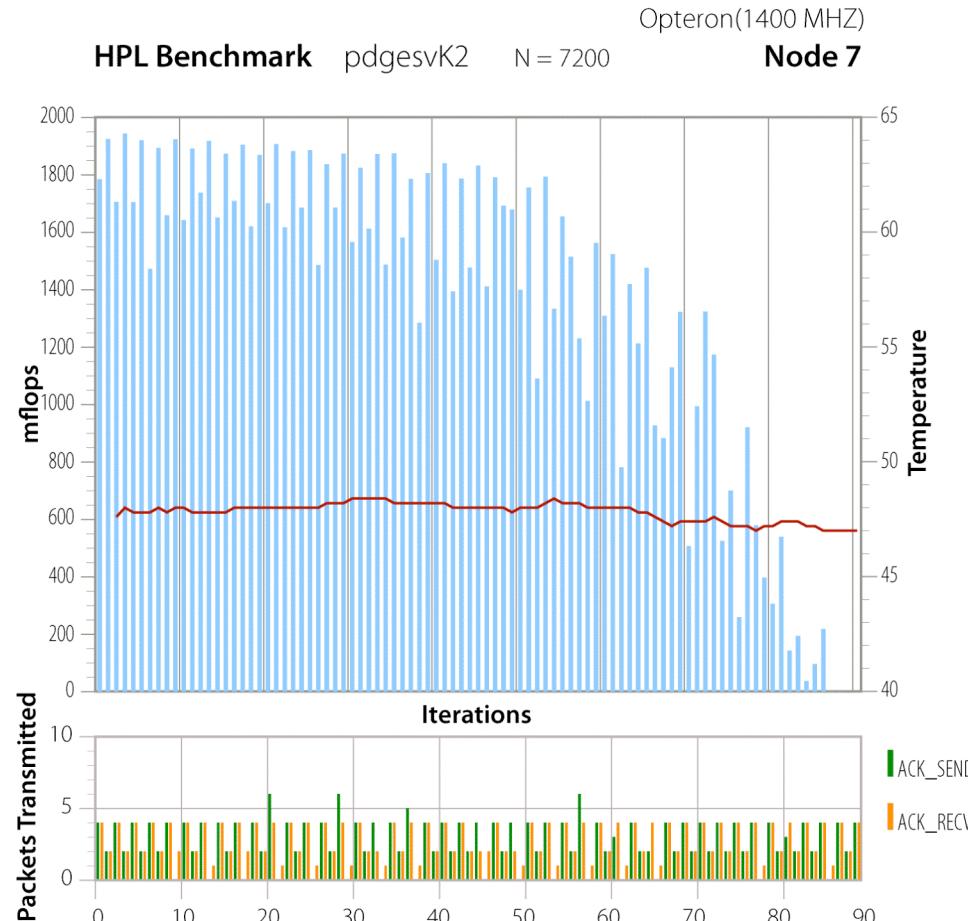


Component PAPI 4.0 design



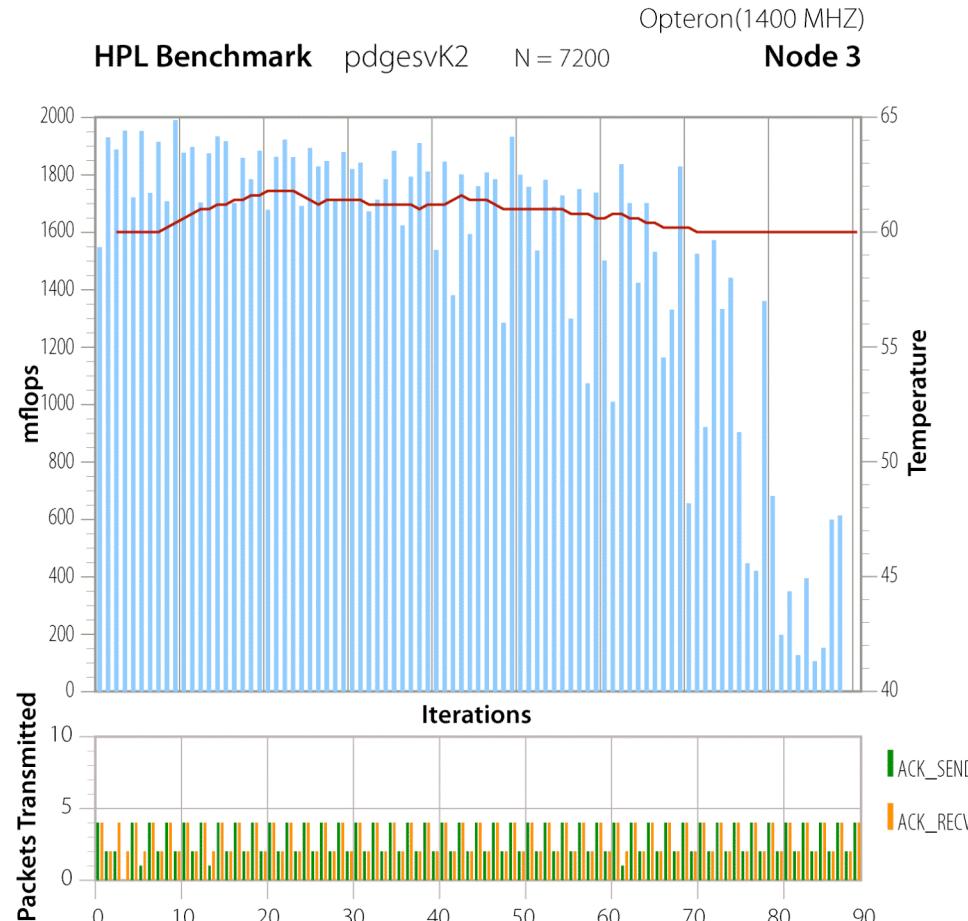
Multiple measurements

- HPCC HPL benchmark on Opteron with three performance metrics:
 - FLOPS; temperature; network sends/receives
 - Temperature is from an on-chip thermal diode.



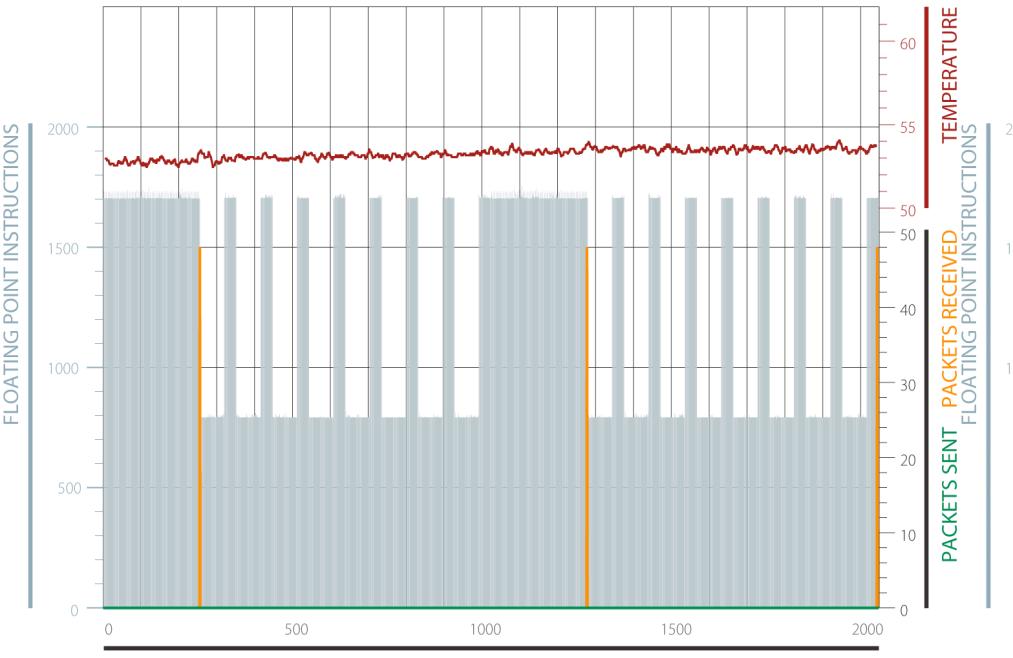
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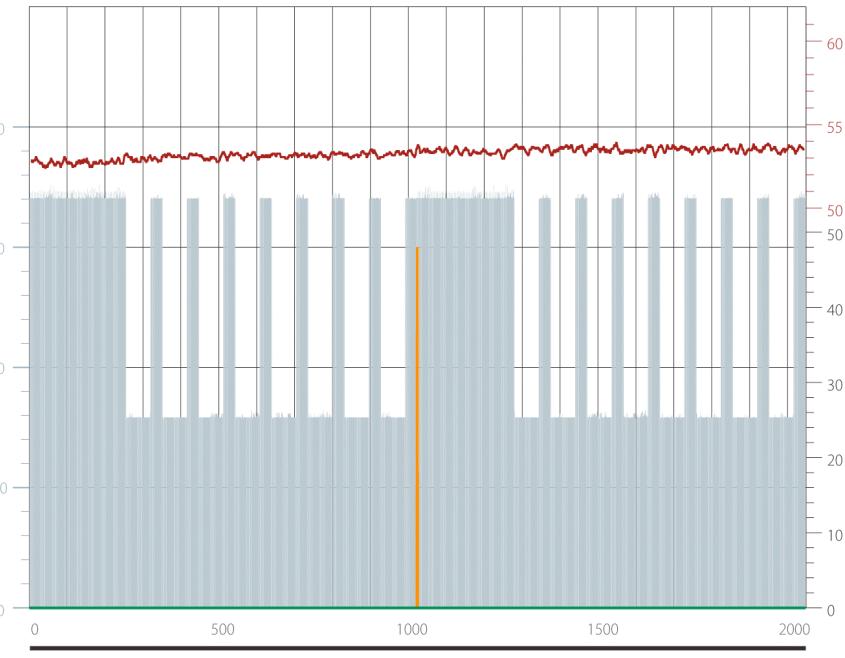


HPC Challenge FFTE: fft235

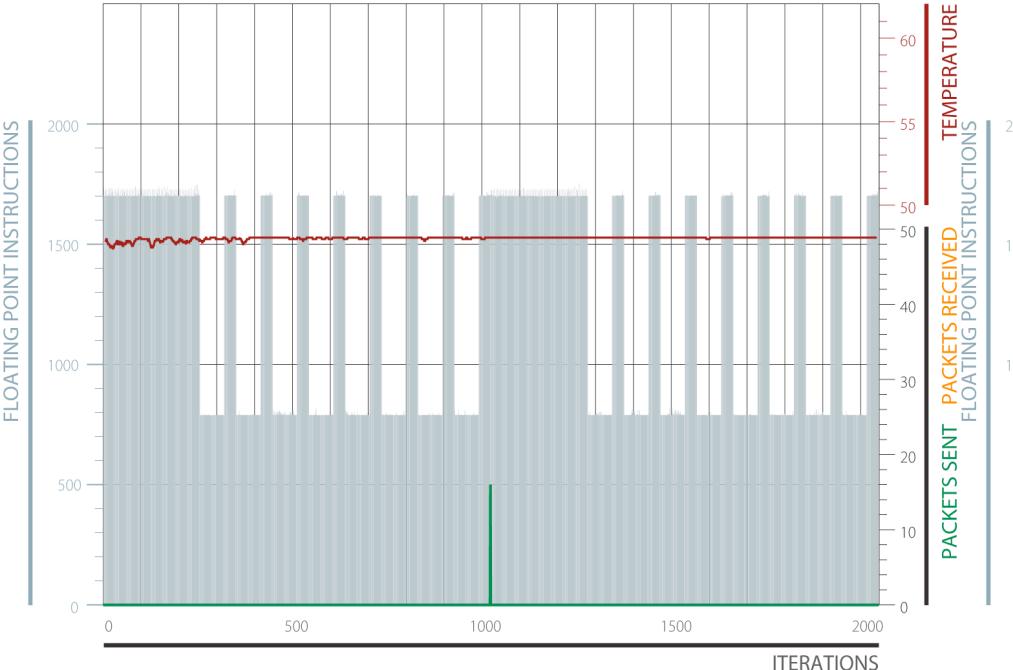
Node 4

**HPC Challenge FFTE: fft235**

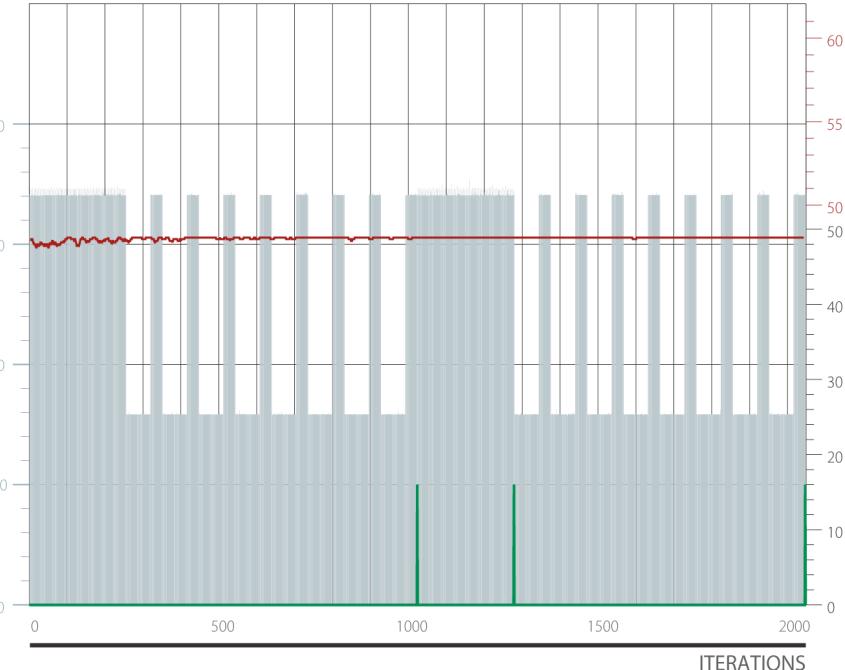
Node 5

**HPC Challenge FFTE: fft235**

Node 6

**HPC Challenge FFTE: fft235**

Node 7



Contacts

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For more information

- <http://icl.cs.utk.edu/papi/>
 - Software and documentation
 - Reference materials
 - Papers and presentations
 - Third-party tools
 - Mailing lists